

## 4.8-5.0GHz, 35W, 28V GaN PA Module

#### **Description**

The GMAH4850-33 is a 35-watt peak power, integrated 2-stage Power Amplifier Module, designed for massive MIMO applications, with frequencies from 4.8 to 5.0 GHz. The module is 50  $\Omega$  input and output and requires minimal external components. The module offers a much smaller footprint than traditional discrete component solutions. The module incorporates a Doherty final stage delivering high power added efficiency for the entire module at 5.6 W average power.



• Typical 1C WCDMA Performance of Doherty Demo (On Innogration fixture with device soldered through grounding vias):

VDS= 28V, Vdriver=-2.4V(25mA), Vmain=-2.19V(50mA), Vpeak=-4V					
Pout(dBm)	Freq (MHz) Ppeak(dBm) Gain (dB) EFF (%) ACPR (				
	4800	46.11	29.8	45.3	-26.5
37.5	4900	46.04	29.9	45.8	-28.2
	5000	45.91	29.9	45.3	-29.8

#### **Features**

- High Efficiency and Linear Gain Operations
- Integrated ESD Protection
- 50 Ω Input / Output
- Integrated Doherty Final Stage
- 6x10 mm Surface Mount Package
- Compliant to Restriction of Hazardous Substances (RoHS) Directive 2002/95/EC

#### **Pin Configuration and Description**



Pin No.	Symbol	Description
1	VD1	Driver Amplifier, Drain Bias
4	VG1	Driver Amplifier, Gate Bias
6	RF IN	RF Input
11	VG3	Carrier Amplifier, Gate Bias
16	Vb	VBW Enhancement Lead
19	RF OUT	RF Output
27	VD2	Peaking Amplifier, Drain Bias
32	VG2	Peaking Amplifier, Gate Bias



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3,8-10,14-15,17,21,22,24,26,28,29,33-35	NC	No connection
2,5,7,12,13,18,20,23,25,30,31,36	GND	Internal Grounding, recommend connecting to Epad ground
		DC/RF Ground. Must be soldered to EVB ground plane over array of
Package Base	GND	vias for thermal and RF performance. Solder voids under Pkg Base will
_		result in excessive junction temperatures causing permanent damage.

#### **Table 1. Maximum Ratings**

Rating	Symbol	Value	Unit
DrainSource Voltage	V <sub>DSS</sub>	150	Vdc
GateSource Voltage	V <sub>GS</sub>	-10 to +2	Vdc
Operating Voltage	V <sub>DD</sub>	+40	Vdc
Storage Temperature Range	Tstg	-65 to +150	°C
Case Operating Temperature	Tc	+150	°C
Operating Junction Temperature	T₃	+225	°C

#### **Table 2. Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Thermal Resistance@Average Power, Junction to Case			
Tcase=+85℃, Tch=126.5℃, CW Test, Pdiss=9W,	Rejc	4.7	°C/W
Pout=5W,			

#### Notes:

- (1) The thermal resistance is acquired by our company's FEA model, which was calibrated by IR measurement, the value shall be applied to reliability.
- (2) The reference Tcase temperature  $85^{\circ}$ C is apply on the backside of package.
- (3) If the device soldering onto the 20mil Rogers PCB with 50 × Φ0.4mm via hole beneath the package backside and the reference temperature Tcase (85°C) apply on the groundside of the PCB, the total thermal resistance R θ JC=TBD°C/W.
- (4) The power dissipation in the table is overall dissipation which include Carrier PA, Peaking PA and driver PA.

#### **Table 3. ESD Protection Characteristics**

Test Methodology	Class Voltage
Human Body Model(HBM) (JEDEC Standard JESD-A114)	±225V
Charged Device Model (CDM) (JEDEC Standard JESD22-C101F)	±1000V

#### Table 4. Electrical Characteristics

Parameter	Condition	Min	Тур	Max	Unit
Frequency Range		4.8		5.0	GHz
Driver Quiescent Current (I <sub>DQ1</sub> )			25		mA
Carrier Quiescent Current (I <sub>DQ3</sub> )			50		mA
Peak PA Gate Quiescent Voltage (V <sub>G2</sub> )			-4		V
Power Gain @ P1dB	Freq=5.0GHz		29		dB
P1dB	Freq=5.0GHz		44.8		dBm
P3dB	Freq=5.0GHz		45.5		dBm
Drain Efficiency@ P3dB Freq=5.0GHz			55.5		%
Unless otherwise noted: TA = 25°C, V <sub>D1</sub> , 2 =	·	cycle=10%	55.5		

Load Mismatch of per Section (On Test Fixture, 50 ohm system):  $V_{D1.2} = 28 \text{ V}$ ,  $I_{DQ1} = 25 \text{ mA}$ ,  $I_{DQ3} = 50 \text{ mA}$ ,  $V_{G2} = -4 \text{ V}$ , f = 5.0 GHz

VSWR 10:1 at P3dB pulse CW Output Power	No Device Degradation
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## Reference Circuit of Test Fixture Assembly Diagram

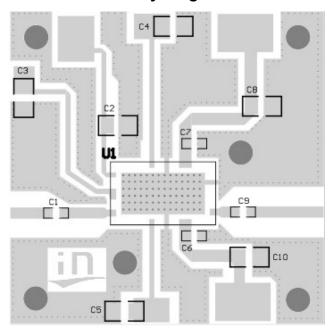


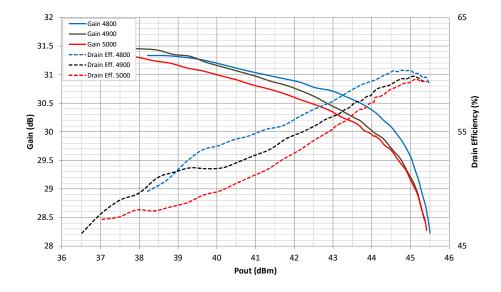
Figure 1. Test Circuit Component Layout

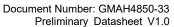
Table 5. Test Circuit Component Designations and Values

Component	Value	Description
U1	GMAH4850_33	PA Module
C1、C7、C9	3.9pF	ATC600S
C2、C3、C4、C5、C8	10uF	TDK1206

### **TYPICAL CHARACTERISTICS**

Figure 2. Power Gain and Drain Efficiency as Function of Pulse Output Power







	VDS= 28V, Vpeak=-4.0V,IDQ1=25mA, IDQ2=50mA				
Freq (MHz)	P-1(dBm)	P-1Gain (dB)	P-3(dBm)	EFF (%)	
4800	44.32	30.2	45.50	59.2	
4900	43.14	30.4	45.36	59.4	
5000	42.93	30.4	45.42	59.4	

Figure 2. S11/S21 output from Network analyzer

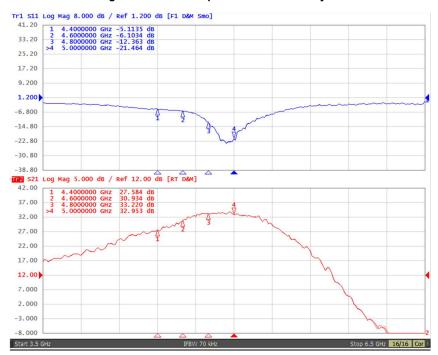
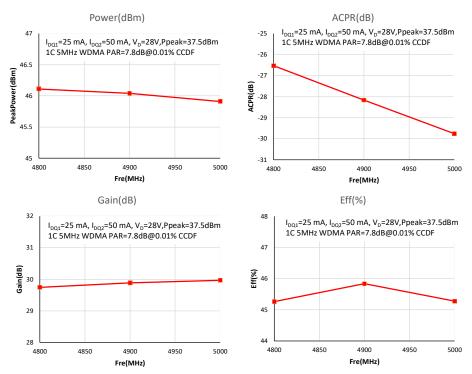
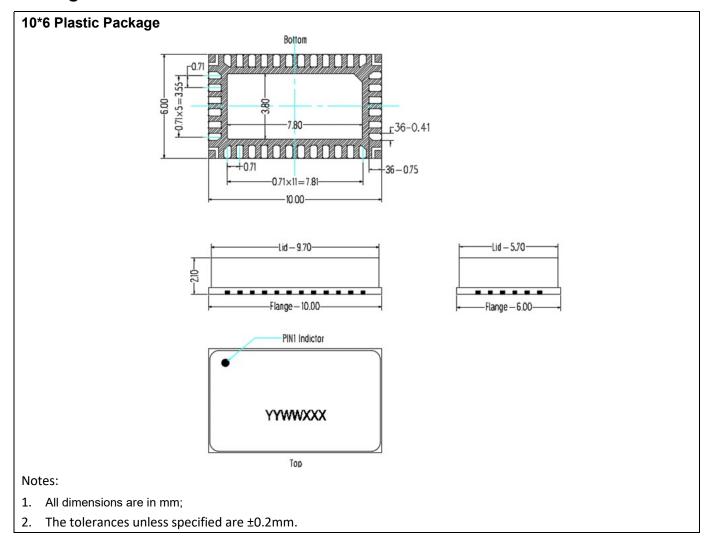


Figure 3: ACPR,efficiency,power gain, peak power across the band @37.5dBm output

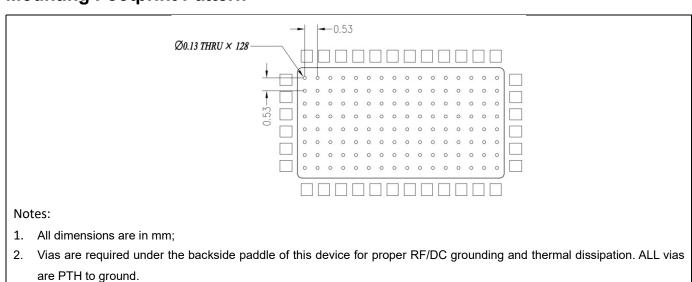


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## **Package Dimensions**



## **Mounting Footprint Pattern**





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#### **Revision history**

Table 6. Document revision history

Date	Revision	Datasheet Status
2020/10/14	Rev 1.0 Preliminary datasheet creation	

Application data based on HJ-20-25

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